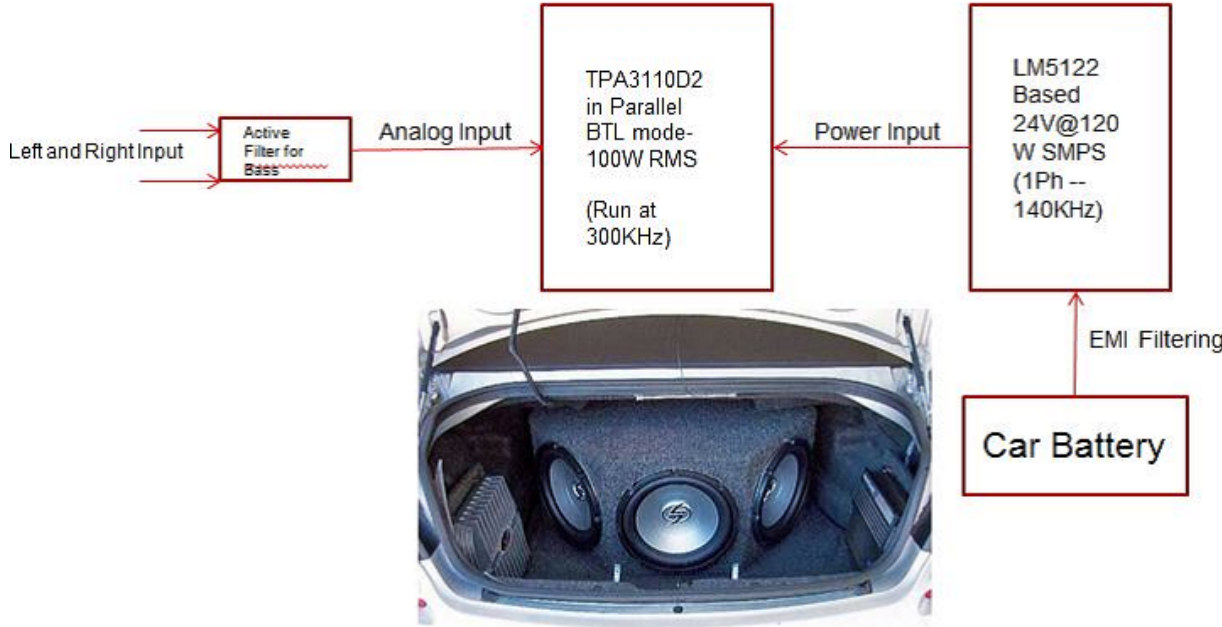
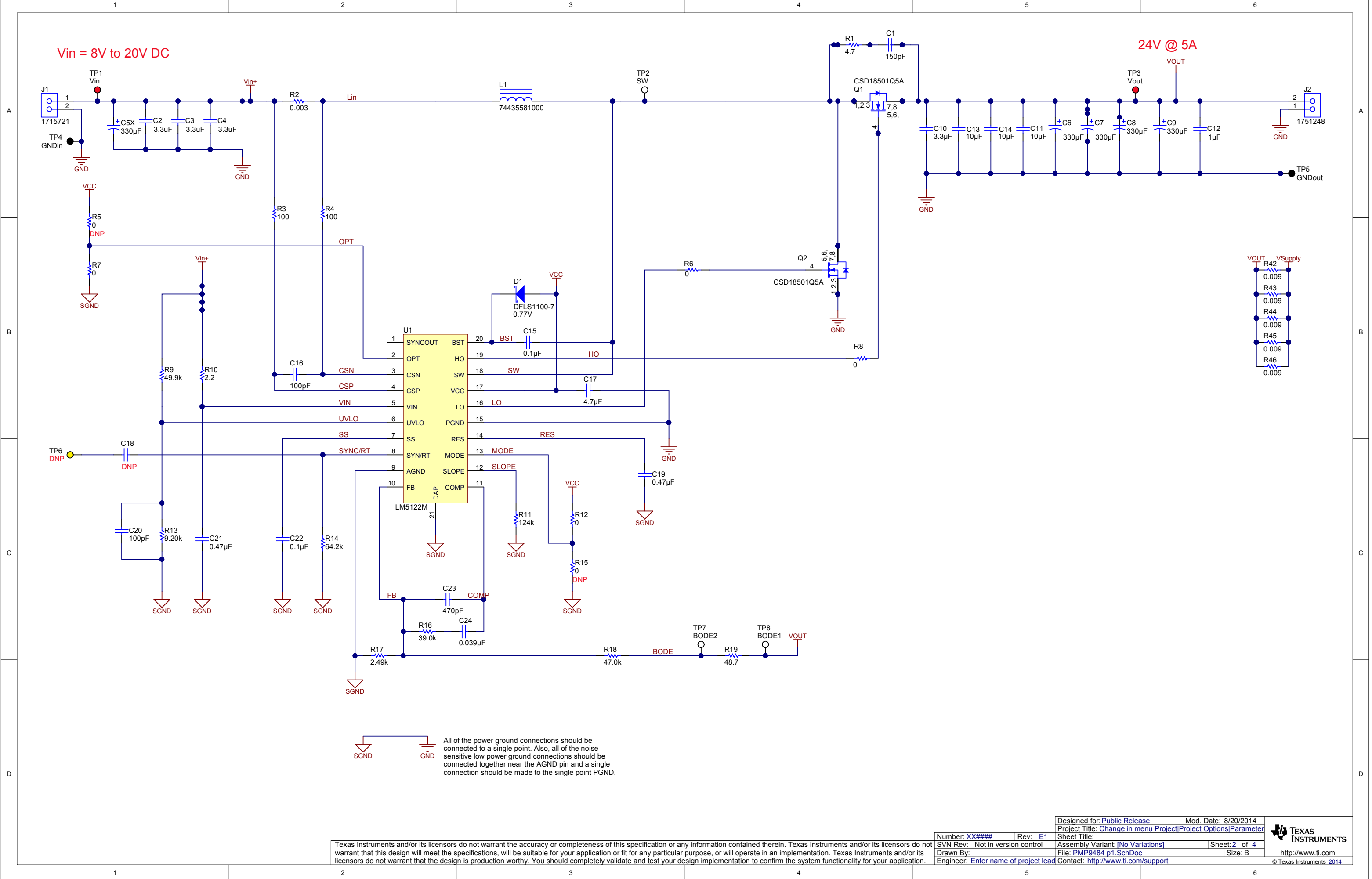
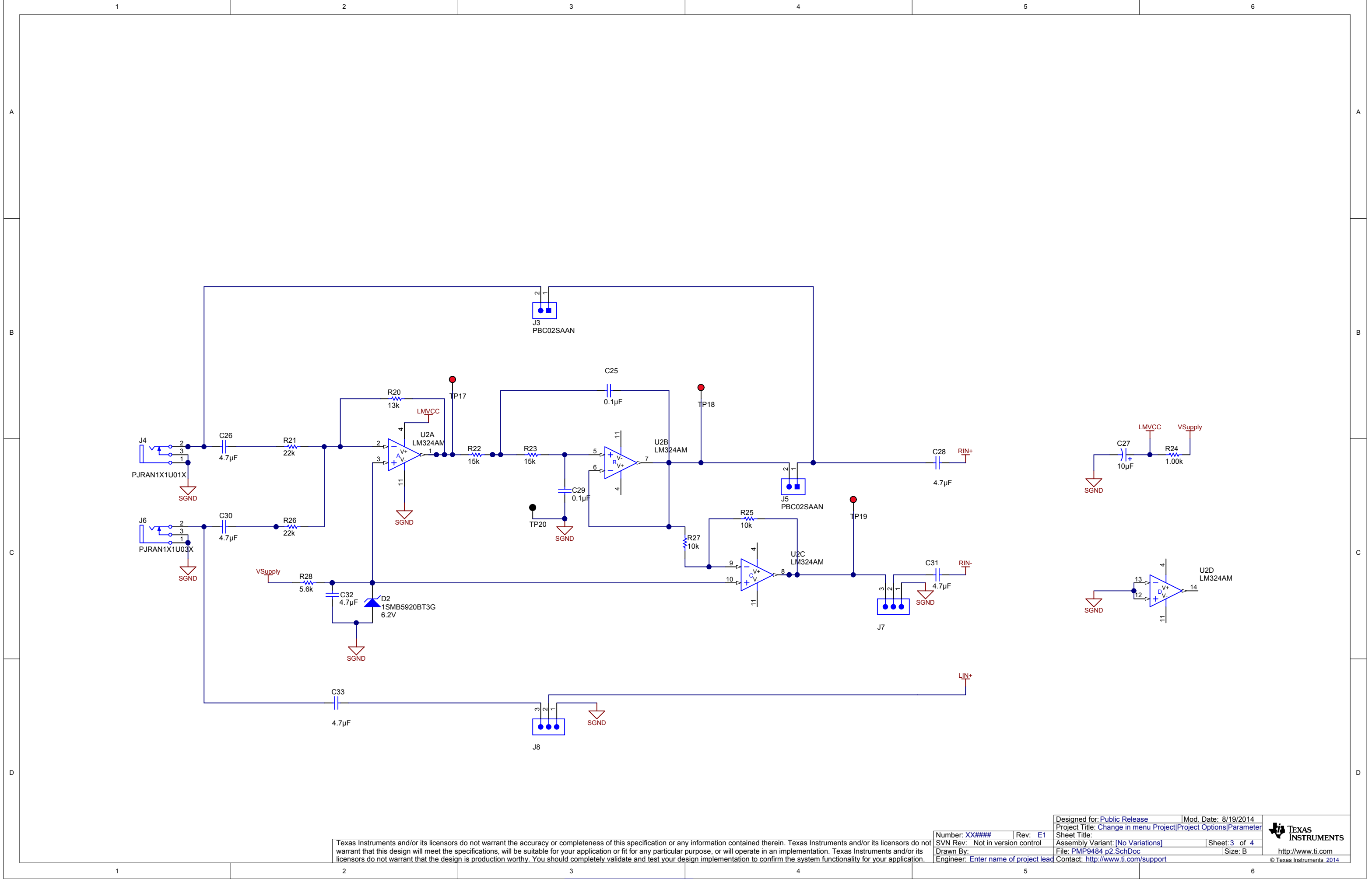


Revision History	
Revision	Notes

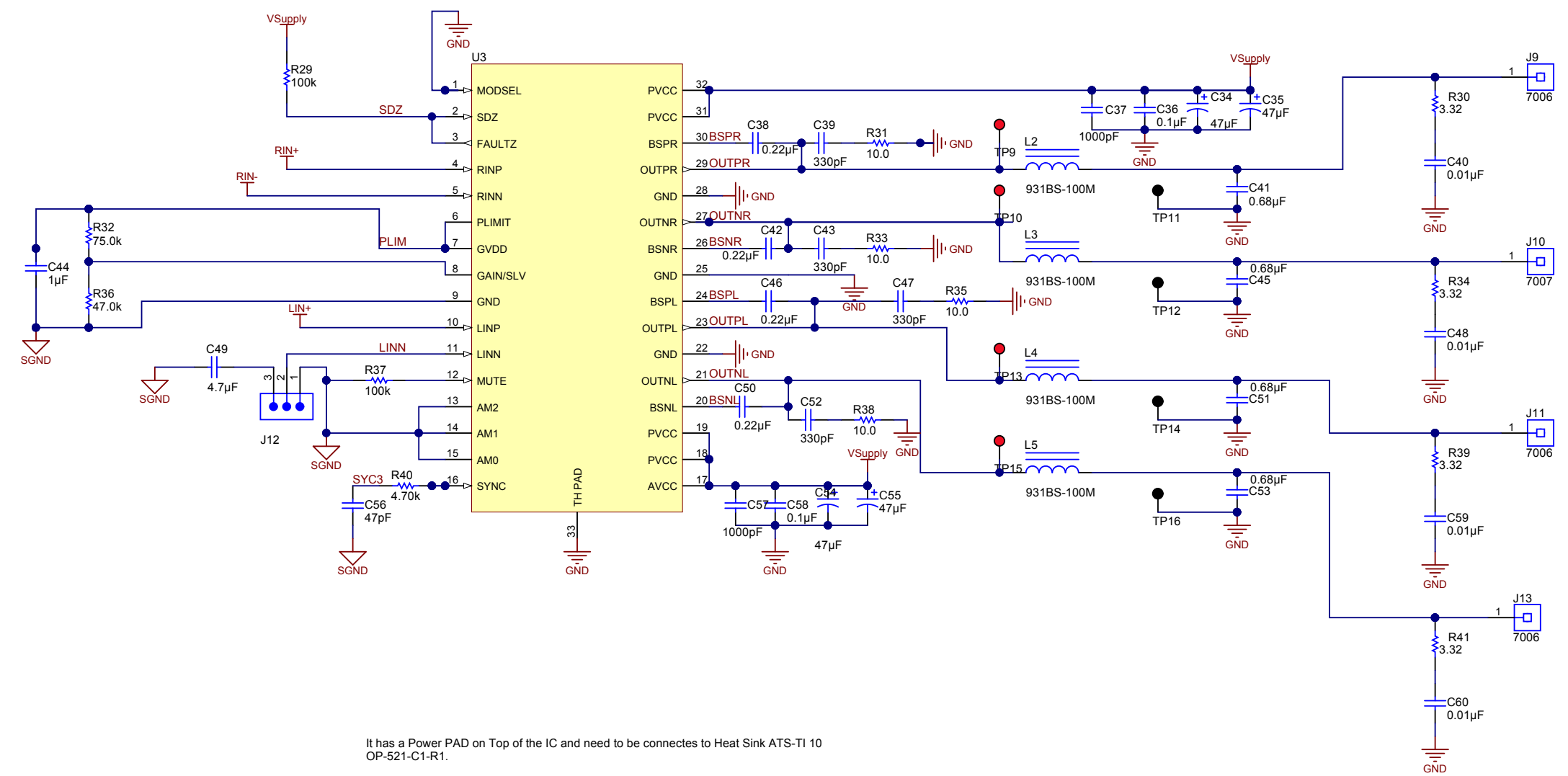






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It has a Power PAD on Top of the IC and need to be connects to Heat Sink ATS-TI 10 OP-521-C1-R1.



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